

Aditya P Karmarkar

List of Publications by Year in descending order

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8
papers

173
citations

1937685
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2272923
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8
all docs

8
docs citations

8
times ranked

105
citing authors

#	ARTICLE	IF	CITATIONS
1	Performanace and reliability analysis of 3D-integration structures employing Through Silicon Via (TSV). , 2009, , .		96
2	Material, Process and Geometry Effects on Through-Silicon Via Reliability and Isolation. Materials Research Society Symposia Proceedings, 2010, 1249, 1.	0.1	20
3	3D TCAD Modeling For Stress Management In Through Silicon Via (TSV) Stacks. AIP Conference Proceedings, 2011, , .	0.4	16
4	Simulation methodology and flow integration for 3D IC stress management. , 2010, , .		13
5	Modeling Copper Plastic Deformation and Liner Viscoelastic Flow Effects on Performance and Reliability in Through Silicon Via (TSV) Fabrication Processes. IEEE Transactions on Device and Materials Reliability, 2019, 19, 642-653.	2.0	11
6	Modeling of interconnect stress evolution during BEOL process and packaging. , 2013, , .		9
7	Viscoelastic Modeling and Reliability Assessment of Microelectronics Packages. Materials Research Society Symposia Proceedings, 2009, 1158, 1.	0.1	4
8	Analysis of copper plasticity impact in TSV-middle and backside TSV-last fabrication processes. , 2015, , .		4